

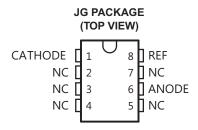
SLVSB44-JULY 2012

CLASS V, PRECISION PROGRAMMABLE REFERENCE

Check for Samples: TL1431-SP

FEATURES

- QMLV Qualified, SMD 5962-99620
- 0.4% Initial Voltage Tolerance
- 0.2-Ω Typical Output Impedance
- Fast Turnon...500 ns
- Sink Current Capability...1 mA to 100 mA
- Low Reference Current (REF)
- Adjustable Output Voltage...V_{I(ref)} to 36 V



NC - No internal connection

DESCRIPTION/ORDERING INFORMATION

The TL1431 is a precision programmable reference with specified thermal stability over automotive, commercial, and military temperature ranges. The output voltage can be set to any value between $V_{l(ref)}$ (approximately 2.5 V) and 36 V with two external resistors. This device has a typical output impedance of 0.2 Ω . Active output circuitry provides a very sharp turnon characteristic, making the device an excellent replacement for Zener diodes and other types of references in applications such as onboard regulation, adjustable power supplies, and switching power supplies.

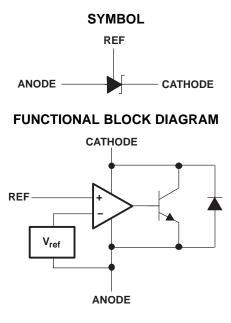
The TL1431 is characterized for operation over the full military temperature range of -55°C to 125°C.

ORDERING INFORMATION⁽¹⁾

T _A	PACK	AGE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
–55°C to 125°C	CDIP – JG	Tube of 50	5962-9962001VPA	9962001VPA	
-55°C 10 125°C	CFP – U	TBD	5962-9962001VHA (Preview)	9962001VHA	

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.





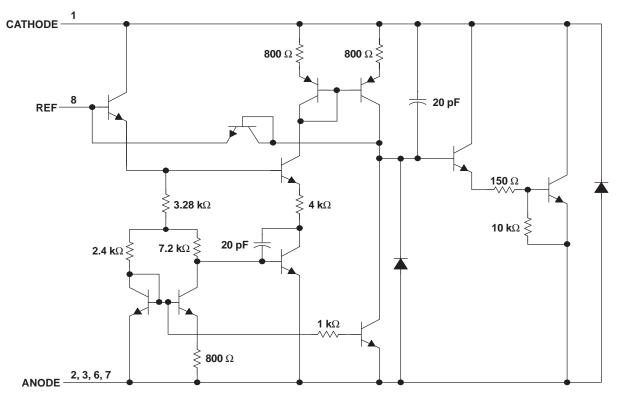
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EQUIVALENT SCHEMATIC



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{KA}	Cathode voltage ⁽²⁾			37	V
I _{KA}	Continuous cathode current range		-100	150	mA
I _{I(ref)}	Reference input current range		-0.05	10	mA
•	Package thermal impedance ^{(3) (4)}	JG package		14.5	°C/W
θ_{JC}	Package inernal impedance (7.0)	U package		TBD	°C/vv
TJ	Operating virtual junction temperature			150	°C
	Lead temperature	1,6 mm (1/16 in) from case for 10 s		260	°C
T _{stg}	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

All voltage values are with respect to ANODE, unless otherwise noted. (2)

Maximum power dissipation is a function of $T_{J(max)}$, θ_{JC} , and T_{C} . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_{J(max)} - T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability. The package thermal impedance is calculated in accordance with MIL-STD-883. (3)

(4)

Recommended Operating Conditions

		MIN	MAX	UNIT
V _{KA}	Cathode voltage	V _{I(ref)}	36	V
I _{KA}	Cathode current	1	100	mA
T _A	Operating free-air temperature	-55	125	°C



Electrical Characteristics

at specified free-air temperature, $I_{KA} = 10$ mA (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	T _A ⁽¹⁾	TEST CIRCUIT	MIN	ТҮР	МАХ	UNIT
			25°C		2475	2500	2540	
V _{I(ref)}	Reference input voltage	$V_{KA} = V_{I(ref)}$	Full range	Figure 1	2460		2550	mV
V _{I(dev)}	Deviation of reference input voltage over full temperature range ⁽²⁾	V _{KA} = V _{I(ref)}	Full range	Figure 1		17	55 ⁽³⁾	mV
$\frac{\Delta V_{\text{I(ref)}}}{\Delta V_{\text{KA}}}$	Ratio of change in reference input voltage to the change in cathode voltage	$\Delta V_{KA} = 3 V \text{ to } 36 V$	Full range	Figure 2		-1.1	-2	mV/V
			25°C			1.5	2.5	
I _{I(ref)}	Reference input current	R1 = 10 kΩ, R2 = ∞	Full range	Figure 2			5	μA
I _{I(dev)}	Deviation of reference input current over full temperature range ⁽²⁾	R1 = 10 kΩ, R2 = ∞	Full range	Figure 2		0.5	3 ⁽³⁾	μA
I _{min}	Minimum cathode current for regulation	$V_{KA} = V_{I(ref)}$	25°C	Figure 1		0.45	1	mA
			25°C			0.18	0.5	
l _{off}	Off-state cathode current	$V_{KA} = 36 \text{ V}, V_{I(ref)} = 0$	Full range	Figure 3			2	μA
z _{KA}	Output impedance ⁽⁴⁾	$V_{KA} = V_{I(ref)}, f \le 1 \text{ kHz},$ $I_{KA} = 1 \text{ mA to } 100 \text{ mA}$	25°C	Figure 1		0.2	0.4	Ω

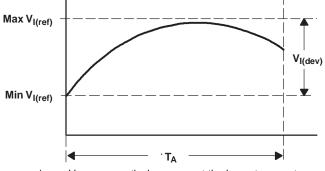
Full range is -55°C to 125°C. (1)

The deviation parameters $V_{I(dev)}$ and $I_{I(dev)}$ are defined as the differences between the maximum and minimum values obtained over the rated temperature range. The average full-range temperature coefficient of the reference input voltage $\alpha_{VI(ref)}$ is defined as: (2)

$$\alpha_{v_{l(ref)}} \left| \left(\frac{ppm}{^{\circ}C} \right) = \frac{\left(\frac{\sqrt{l(dev)}}{V_{l(ref)} at 25^{\circ}C} \right) \times 10^{6}}{T_{A}}$$

where:

 ΔT_A is the rated operating temperature range of the device.



(3)

 $\begin{array}{l} \alpha_{VI(ref)} \text{ is positive or negative, depending on whether minimum } V_{I(ref)} \text{ or maximum } V_{I(ref)}, \text{ respectively, occurs at the lower temperature.} \\ \text{On products compliant to MIL-PRF-38535, this parameter is not production tested.} \\ \text{The output impedance is defined as:} & |z_{\kappa A}| = \frac{\Delta V_{\kappa A}}{\Delta I_{\kappa A}} \\ \text{When the device is operating with two external resistors (see Figure 2), the total dynamic impedance of the circuit is given by:} \\ |z'| = \frac{\Delta V}{\Delta I}, \text{ which is approximately equal to } |z_{\kappa A}| \left(1 + \frac{R1}{R2}\right). \end{array}$ (4)

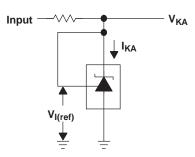
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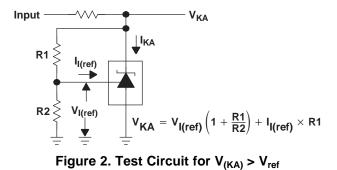
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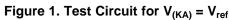


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PARAMETER MEASUREMENT INFORMATION







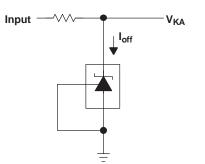


Figure 3. Test Circuit for Ioff

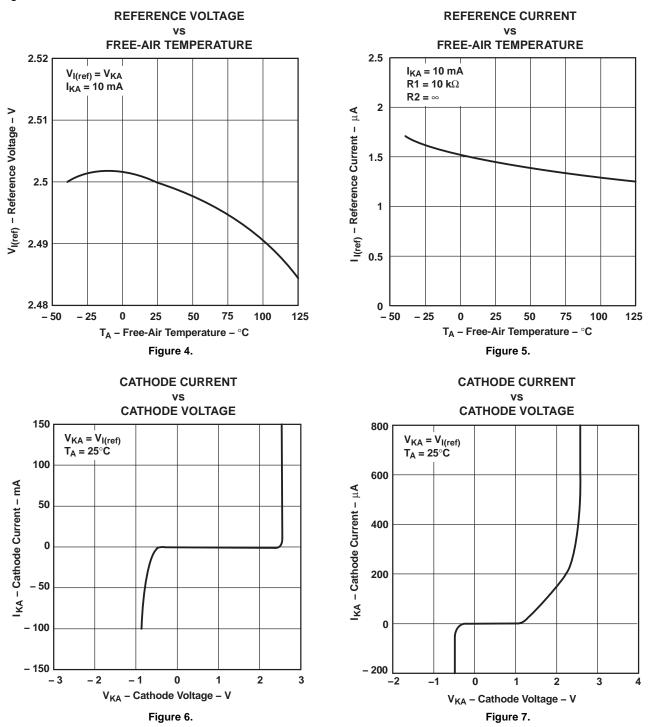


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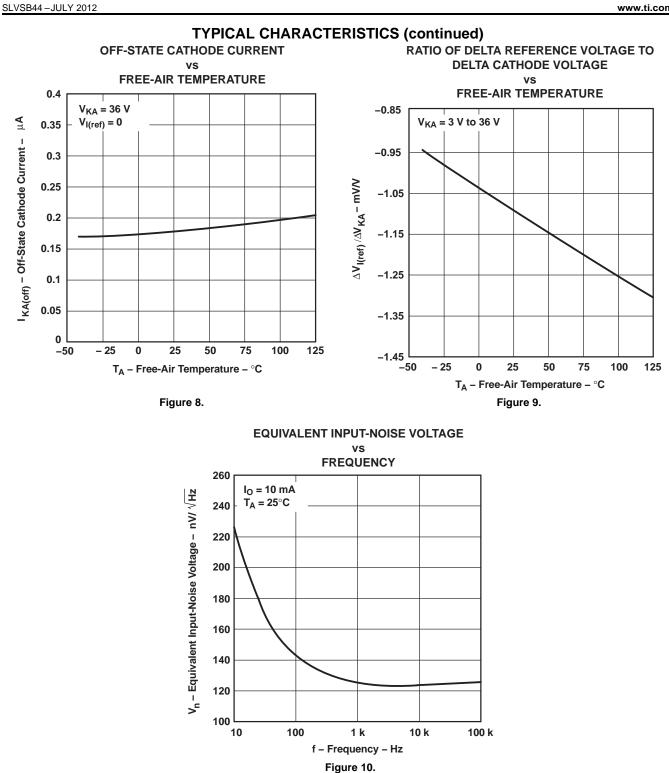
TYPICAL CHARACTERISTICS

Data at high and low temperatures are applicable only within the recommended operating free-air temperature ranges of the various devices.



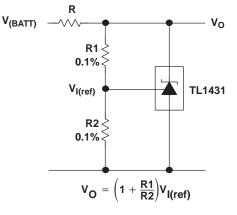
ÈXAS NSTRUMENTS

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A. R should provide cathode current ≥ 1 mA to the TL1431 at minimum V_(BATT).



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STRUMENTS

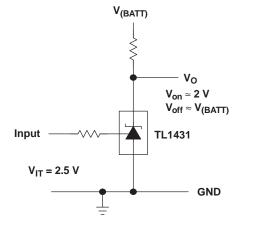
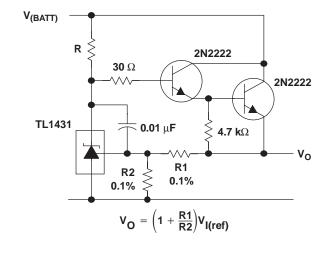
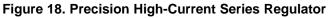


Figure 16. Shunt Regulator



A. R should provide cathode current \geq 1 mA to the TL1431 at minimum V_(BATT).





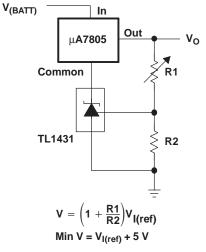


Figure 19. Output Control of a Three-Terminal Fixed Regulator

Submit Documentation Feedback

A. Refer to the stability boundary conditions in Figure 15 to determine allowable values for C.

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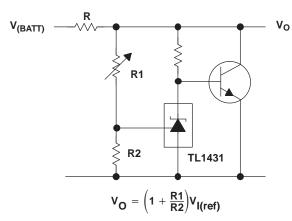


Figure 20. Higher-Current Shunt Regulator

A. R_b should provide cathode current ≥ 1 mA to the TL1431.

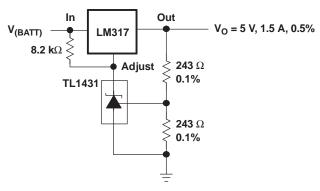


Figure 22. Precision 5-V, 1.5-A, 0.5% Regulator

 $V_{\text{(BATT)}} \longrightarrow V_{0}$ R1 TL1431 C R2 $V_{\text{trip}} = \left(1 + \frac{R1}{R2}\right)V_{\text{l(ref)}}$

Figure 21. Crowbar

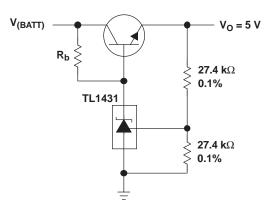
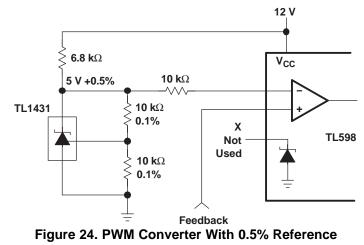


Figure 23. 5-V Precision Regulator

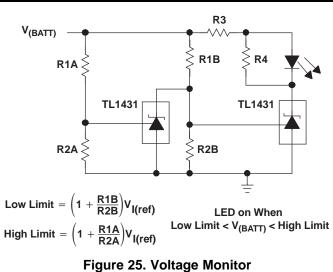


A. Select R3 and R4 to provide the desired LED intensity and cathode current ≥1 mA to the TL1431.

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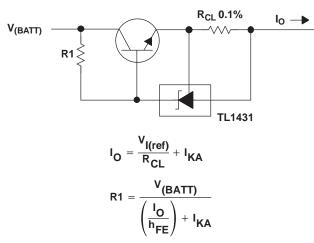


Figure 27. Precision Current Limiter

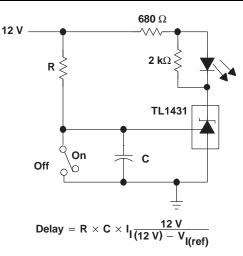


Figure 26. Delay Timer

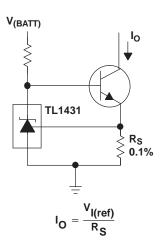


Figure 28. Precision Constant-Current Sink

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-9962001VPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF TL1431-SP :

Catalog: TL1431

• Automotive: TL1431-Q1

Enhanced Product: TL1431-EP

PACKAGE OPTION ADDENDUM



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5-Oct-2011

Military: TL1431M

- NOTE: Qualified Version Definitions:
 - Catalog TI's standard catalog product
 - Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
 - Enhanced Product Supports Defense, Aerospace and Medical Applications
 - Military QML certified for Military and Defense Applications

MECHANICAL DATA

MCER001A - JANUARY 1995 - REVISED JANUARY 1997



CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8



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